

**Breakover diodes**

**BRS212 series**

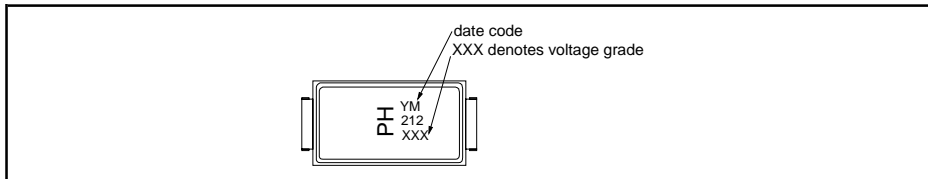
**GENERAL DESCRIPTION**

A range of bidirectional, breakover diodes in a two terminal, surface mounting, plastic envelope. These devices feature controlled breakover voltage and high holding current together with high peak current handling capability. Their intended application is protection of line based telecommunications equipment against voltage transients.

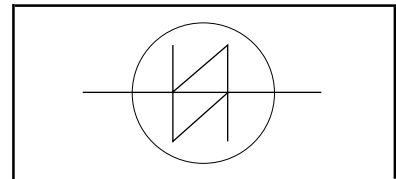
**QUICK REFERENCE DATA**

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
$V_{(BO)}$	Breakover voltage				
	BRS212-140	-	140	-	V
	BRS212-160	-	160	-	V
	BRS212-180	-	180	-	V
	BRS212-200	-	200	-	V
	BRS212-220	-	220	-	V
	BRS212-240	-	240	-	V
	BRS212-260	-	260	-	V
$I_H$	Holding current	150	-	-	mA
	$I_{PP}$ Non-repetitive peak pulse current (CCITT K17)	-	-	40	A

**OUTLINE - SOD106**



**SYMBOL**



**LIMITING VALUES**

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_D$	Continuous voltage	BRS212-140	-	105	V
		BRS212-160	-	120	V
		BRS212-180	-	135	V
		BRS212-200	-	150	V
		BRS212-220	-	165	V
		BRS212-240	-	180	V
		BRS212-260	-	195	V
		BRS212-280	-	210	V
$I_{PP}$	Non-repetitive peak pulse current	5/310 $\mu$ s impulse equivalent to 10/700 $\mu$ s, 1.6 kV voltage impulse (CCITT K17)	-	40	A
$I_{TSM}$	Non repetitive surge peak on-state current	half sine wave; t = 10 ms; $T_j = 70^\circ\text{C}$ prior to surge	-	15	A
$I^2t$	$I^2t$ for fusing	$t_p = 10$ ms	-	1.1	A <sup>2</sup> s
$dl_T/dt$	Rate of rise of on-state current after $V_{(BO)}$ turn-on	$t_p = 10$ $\mu$ s	-	50	A/ $\mu$ s
$P_{tot}$	Continuous dissipation on infinite heatsink	$T_{sp} = 50^\circ\text{C}$	-	4	W
$P_{TM}$	Peak dissipation	$t_p = 1$ ms; $T_a = 25^\circ\text{C}$	-	50	W
$T_{stg}$	Storage temperature		- 40	150	$^\circ\text{C}$
$T_j$	Operating junction temperature		-	150	$^\circ\text{C}$
$T_L$	Maximum terminal temperature for soldering	soldering time = 10 s	-	260	$^\circ\text{C}$

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## THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j-sp}$	Thermal resistance junction to solder point		-	-	25	K/W
$R_{th\ j-a}$	Thermal resistance junction to ambient	pcb mounted; minimum footprint	-	100	-	K/W
$Z_{th\ j-a}$	Thermal impedance junction to ambient	$t_p = 1\ ms$	-	2.6	-	K/W

## ELECTRICAL CHARACTERISTICS

$T_j = 25\ ^\circ C$  unless otherwise stated

TYPE	PARAMETER								
	Marking	Avalanche voltage		Breakover voltage		Off-state current		Critical rate of rise of off-state voltage	
Conditions		$I_{BR} = 10\ mA$		$I_D \leq I_S$ $t_p = 100\ \mu s$		$T_j = 70\ ^\circ C$ ; $RH \leq 65\%$		$T_j = 70\ ^\circ C$	
Symbol		$V_{BR}$		$V_{BO}$		$I_D @ V_D$		$dV_D/dt @ V_{DM}$	
Limits		min	typ	typ	max	max		max	
Units		V	V	V	V	$\mu A$	V	V/ $\mu s$	V
BRS212-140	212-140	123	140	140	157	10	105	2000	105
BRS212-160	212-160	140	160	160	180	10	120	2000	120
BRS212-180	212-180	158	180	180	202	10	135	2000	135
BRS212-200	212-200	176	200	200	224	10	150	2000	150
BRS212-220	212-220	193	220	220	247	10	165	2000	165
BRS212-240	212-240	211	240	240	269	10	180	2000	180
BRS212-260	212-260	228	260	260	292	10	195	2000	195
BRS212-280	212-280	246	280	280	314	10	210	2000	210

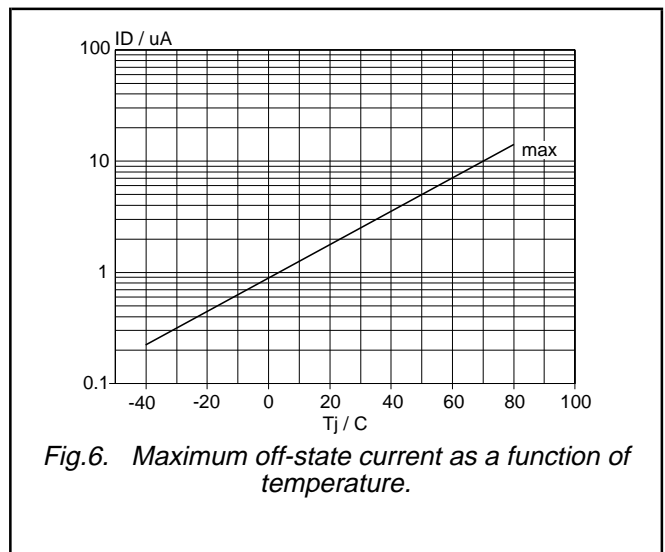
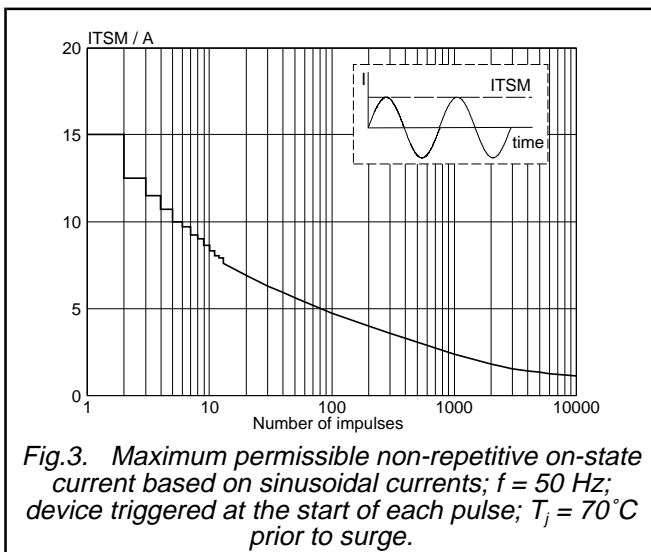
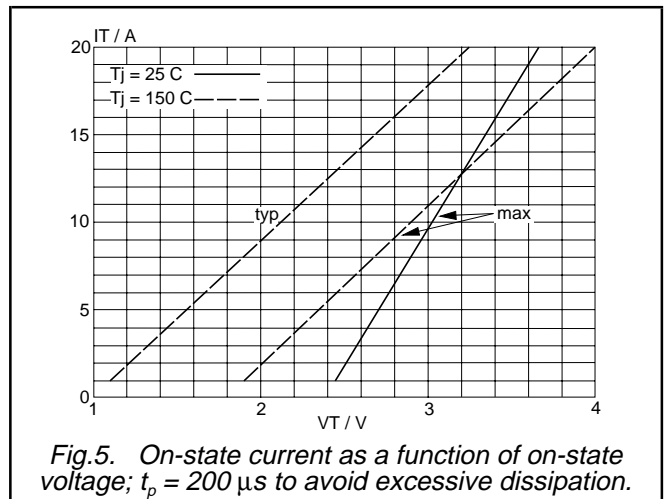
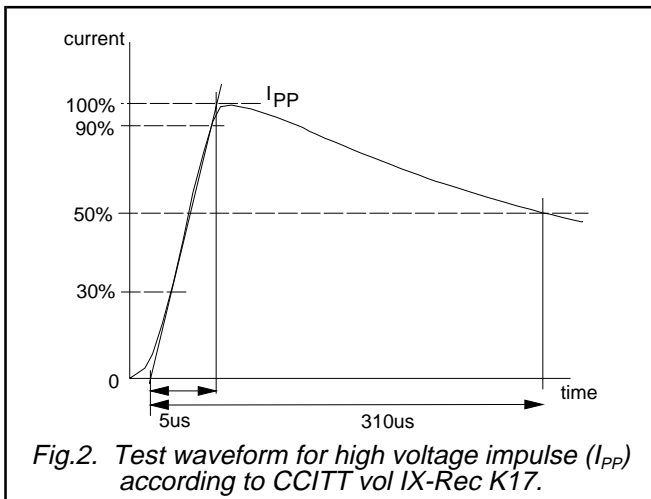
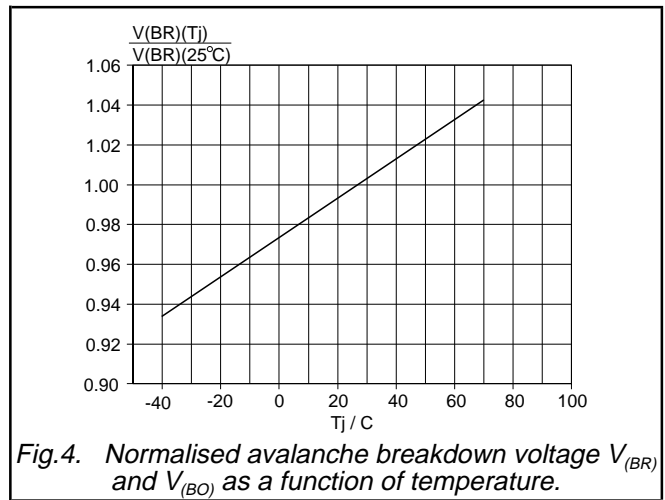
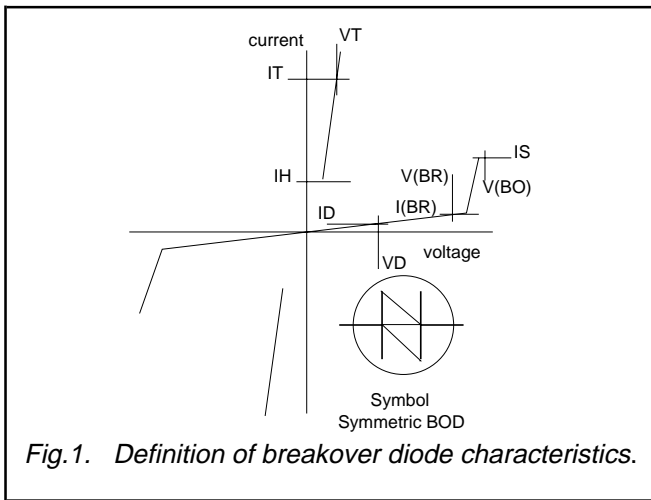
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_T$	On-state voltage	$I_{TM} = 2\ A$ ; $t_p = 200\ \mu s$	-	-	2.5	V
$I_H$	Holding current <sup>1</sup>	$T_j = 25\ ^\circ C$	150	-	-	mA
$I_S$	Switching current <sup>2</sup>	$T_j = 70\ ^\circ C$	100	-	-	mA
$S_{(BR)}$	Temperature coefficient of avalanche voltage	$t_p = 100\ \mu s$	10	200	1000	mA
$C_j$	Junction capacitance	$V_D = 0\ V$ , $f = 1\ kHz\ to\ 1\ MHz$	-	+0.1	-	%/K
			-	-	100	pF

1 The minimum current at which the diode will remain in the on-state

2 The avalanche current required to switch the diode to the on-state.

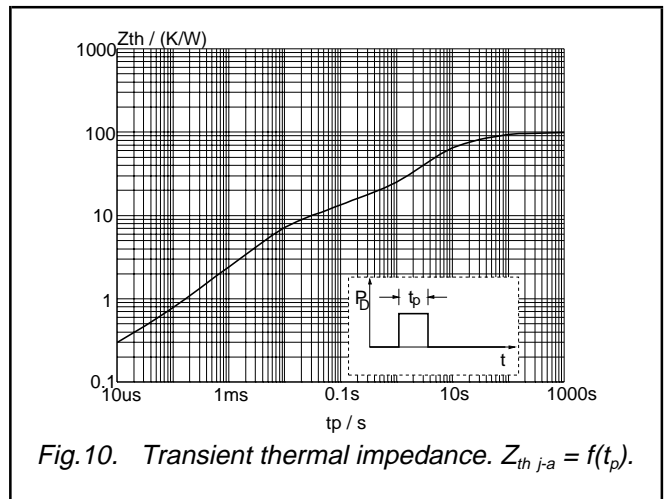
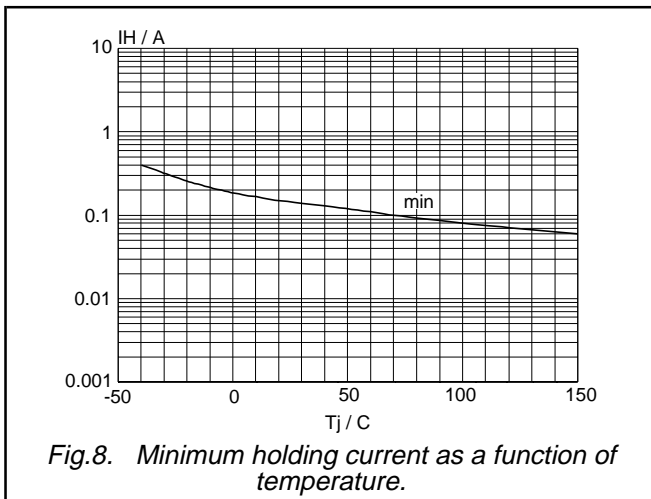
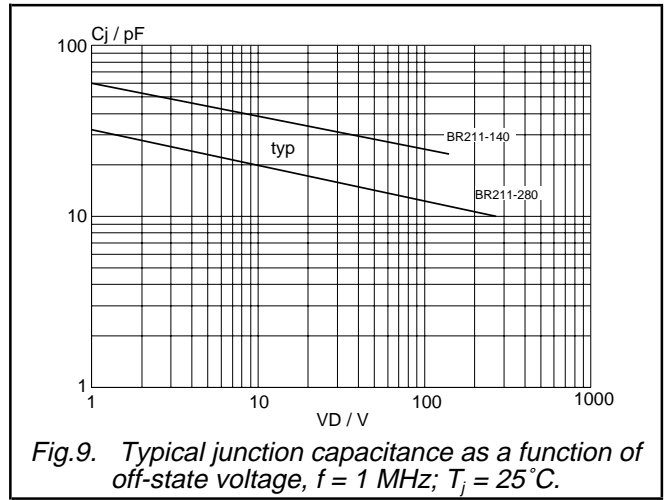
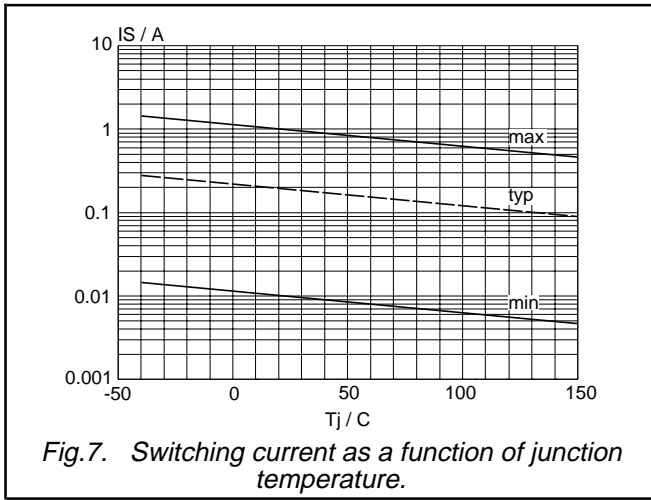
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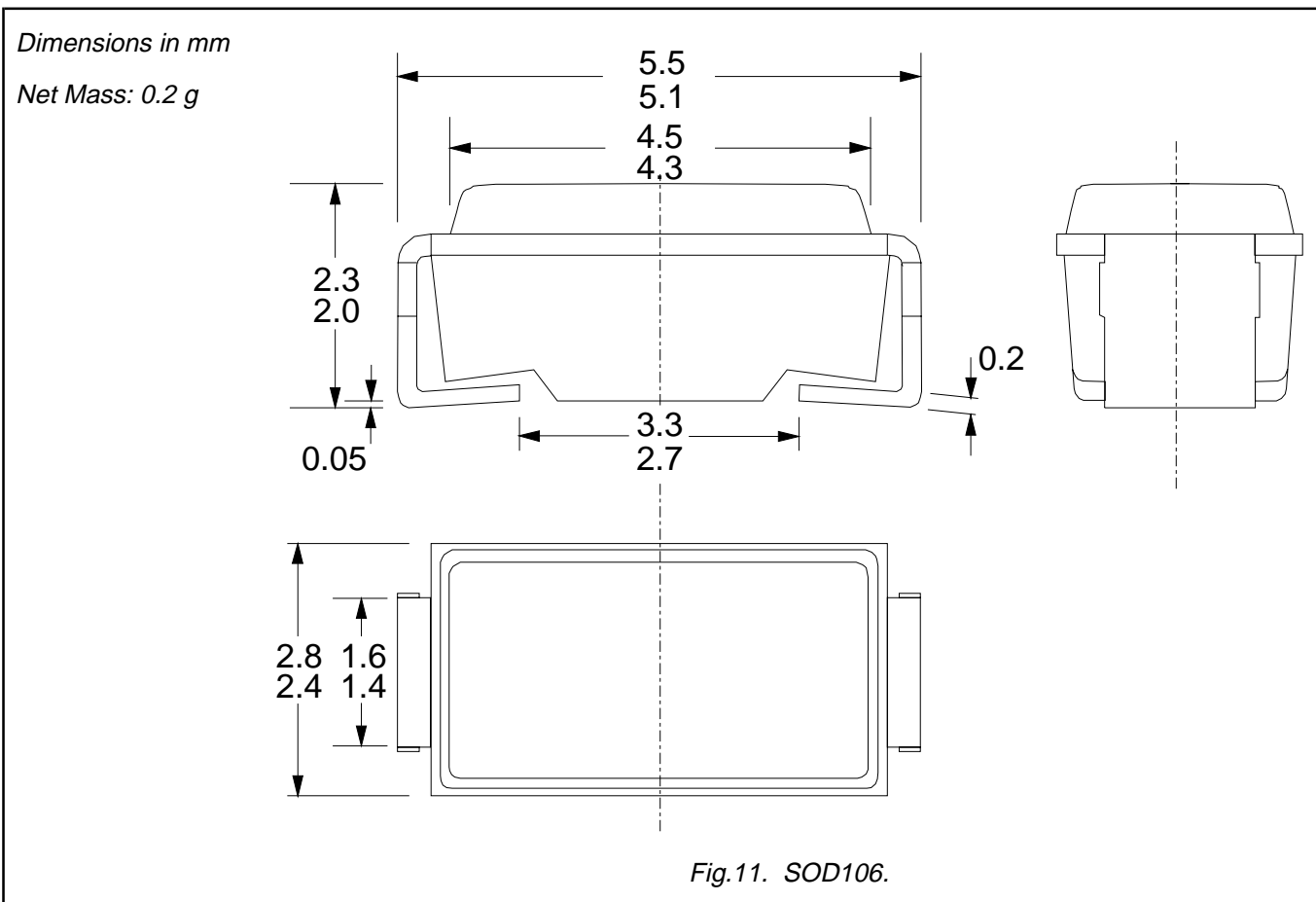


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**MECHANICAL DATA**



**Notes**

- 1. For mounting and soldering instructions refer to publication SC18 "SMD Footprint Design and Soldering Guidelines". Order code:9397 750 00505.

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**DEFINITIONS**

<b>Data sheet status</b>	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
<b>Limiting values</b>	
Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
<b>Application information</b>	
Where application information is given, it is advisory and does not form part of the specification.	
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